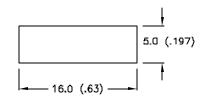
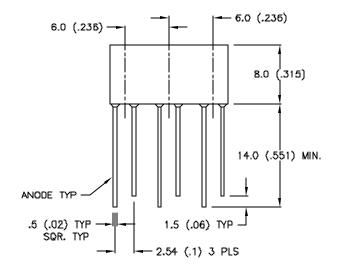
DATE		REVISIONS			
7 —	30 - 95	UPDATED SPECS./	Α	ĺ	

DRAWING NUMBER SSB-LX845YD REV Α





NOTES:

- 1. TOLERANCE: ± 0.2 (± 0.01). 2. UNIT: mm (INCHES).

RELIABILITY NOTE:

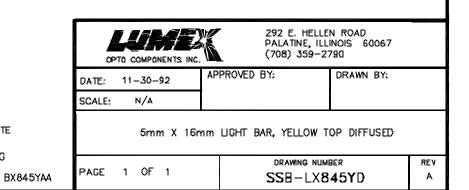
OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.

ELECTRO-OPTICAL CHARACTERISTICS TA=25 °C I =20mA

PARAMETER	MIN	TYP	MAX	UNITS	TEST COND
PEAK WAVELENGTH		585 (\	ŒLLQW)	nm	
FORWARD VOLTAGE		2.0	2.8	٧ _f	
REVERSE VOLTAGE	5.0			٧ _r	Ir=100uA
AXIAL INTENSITY		5.0		med	$I_f = 20 m A$
VIEWING ANGLE		120		2× theta	'
EMITTED COLOR:	YELL	_OW			
EPOXY LENS FINISH:	YELL	OM LOD	DIFFUSED		

PARAMETER MAX UNITS PEAK FORWARD CURRENT* 150 mA STEADY CURRENT 30 mA POWER DISSIPATION 105 mW DERATE FROM 25 °C -1.2 mw/ °C OPERATING, STORAGE TEMP40 TO +85 °C LEAD SOLDERING TEMP. +250 °C 2.0mm FROM BODY 3 SFC. MAX	A LIMITS OF SAFE OPE	ERATION AT 25 DE	G, C
STEADY CURRENT 30 mA POWER DISSIPATION 105 mW DERATE FROM 25 °C -1.2 mW/ °C OPERATING, STORAGE TEMP40 TO +85 °C LEAD SOLDERING TEMP. +260 °C	PARAMETER	MAX	UNITS
POWER DISSIPATION 105 mW DERATE FROM 25 °C −1.2 mW/ • C OPERATING, STORAGE TEMP. −40 TO +85 ° C LEAD SOLDERING TEMP. +260 ° C	PEAK FORWARD CURRENT*	150	mA
DERATE FROM 25 °C −1.2 mW/ °C OPERATING, STORAGE TEMP. −40 TO +85 °C LEAD SOLDERING TEMP. +260 °C	STEADY CURRENT	30	mΑ
OPERATING, STORAGE TEMP40 TO +85 °C LEAD SOLDERING TEMP. +260 °C	POWER DISSIPATION	105	mW
LEAD SOLDERING TEMP. +260 °C	DERATE FROM 25 °C	-1.2	mW/ ◆ C
	OPERATING, STORAGE TEMP.	-40 TO +85	°C
2.0mm FROM BODY 3 SEC. MAX	LEAD SOLDERING TEMP.	+250	• C
	2.0mm FROM BODY		3 SEC. MAX

^{*} t<1Du5



Mouser Electronics

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